

## MEMS and NEMS

### Room 205 ABCD W - Session MN1-FrM

#### Integration and Multiphysics

**Moderators:** Philip Feng, University of Florida, Jaesung Lee, University of Central Florida

8:15am **MN1-FrM-1 MEMS-Enabled Photonic Integrated Circuits**, *Marcel Pruessner, Todd Stievater, Nathan Tyndall, Steven Lipkowitz, Jacob Bouchard, Kyle Walsh*, US Naval Research Laboratory **INVITED**  
Photonic integrated circuits (PICs) are maturing and are rapidly finding application beyond telecommunications, including for sensing and quantum photonics. Many of these applications require PICs that operate at non-telecom wavelengths (e.g. in the visible wavelength spectrum) as well as PICs with new functionality enabled by micro-electro-mechanical systems (MEMS). In collaboration with AIM Photonics, we have developed a foundry PIC platform optimized for visible wavelengths focusing on reducing propagation loss and designing efficient PIC components<sup>1</sup>. At the same time, we have also investigated novel functionality in PICs enabled by MEMS. This presentation will focus on “MEMS-enabled photonic integrated circuits,” their fabrication and incorporation in PIC foundries, and novel functionality enabled by combining PICs with MEMS. A variety of MEMS-enabled PIC devices will be discussed including MEMS-tunable phase shifters<sup>2</sup> and optical cavities<sup>3</sup>, optical forces in cavity optomechanical systems<sup>4</sup>, mode conversion using MEMS perturbation<sup>5</sup> and phase matching<sup>6</sup>, and broadband waveguide thermal emitters<sup>7</sup> enabled by MEMS bulk micromachining techniques<sup>8</sup>.

<sup>1</sup> <https://doi.org/10.1117/12.3012847> and <https://doi.org/10.1364/OE.504195>

<sup>2</sup> <https://doi.org/10.1364/OE.24.013917> and <https://doi.org/10.1364/OSAC.419410>

<sup>3</sup> <https://doi.org/10.1063/1.2883874> and <https://doi.org/10.1364/OL.44.003346>

<sup>4</sup> <https://doi.org/10.1364/OE.19.021904> and <https://doi.org/10.1103/PhysRevLett.108.223904> and <https://doi.org/10.1021/acsphotonics.8b00452>

<sup>5</sup> <https://doi.org/10.1364/OE.488624>

<sup>6</sup> <https://doi.org/10.1364/OL.474806>

<sup>7</sup> <https://doi.org/10.1038/s41467-024-48772-6>

<sup>8</sup> <https://doi.org/10.1063/5.0252536>

8:45am **MN1-FrM-3 Crack-Free Growth and Improved Saturation Magnetization of NiCuZn Ferrite Films by Combining Sputtering and Sol-Gel Methods**, *Sushma Kotru, Roni Paul*, The University of Alabama  
NiCuZn ferrite films exhibit diverse applications in high-frequency wearable electronics, inductors, electromagnetic interference filters, and antennas due to their high resistivity, low eddy current losses, high permeability, and significant saturation magnetization. The demand for depositing thicker films, particularly for power electronics, is increasing. Conventional deposition methods such as electrodeposition and screen printing are limited for integrating NiCuZn ferrite films on Si substrates. In this study, we developed a hybrid approach combining sputtering and sol-gel deposition to prepare films with thicknesses ranging from ~240 nm to 1.8  $\mu\text{m}$ . A thin sputter-deposited NiCuZn ferrite layer served as a seed layer (SL) to enable crack-free thick film growth and to improve magnetic performance upon annealing. Structural analysis was performed using X-ray diffraction (XRD) and field emission scanning electron microscopy (FESEM), while magnetic properties were measured using a vibrating sample magnetometer (VSM). The maximum saturation magnetization of **310 emu/cm<sup>3</sup>** was achieved for a 240 nm-thick film annealed at 800 °C. With increasing thickness, the saturation magnetization decreased slightly, from **310 emu/cm<sup>3</sup> (240 nm) to 280 emu/cm<sup>3</sup> (1.8  $\mu\text{m}$ )**, yet remained higher than previously reported values. The sputtered SL effectively suppressed crack formation during post-annealing above 600 °C and promoted more homogeneous film growth compared to sputtering or sol-gel methods alone. These results demonstrate that the hybrid deposition approach enables high-quality thick ferrite films suitable for **miniaturized inductors and power electronics applications**.

9:00am **MN1-FrM-4 Integration of Metal Microsystems for Gas Sensing**, *David Hayes, Henry Davis, Jeremy Cook, Jordan Grow, James Harkness, Isa Kohls, Richard Vanfleet, Brian Jensen, Nathan Crane, Robert Davis*, Brigham Young University

Microfluidic devices are a versatile and powerful class of analytical and production tools with applications spanning medical diagnostics, drug development, food safety, and chemical production among others. A subset of microfluidic devices are microscale gas chromatography columns, which offer high speed chemical separations and system miniaturization. Hermetic sealing of micro chromatography channels and interfaces are challenges that have inspired a wide range of solutions. We will describe our developments in interfacing to both 3D printed metal microcolumns and machined metal microfluidic structures using pressure-controlled microbrazing.

9:15am **MN1-FrM-5 Nanomechanical Resonances of Graphene Membranes Integrated on LiNbO<sub>3</sub>-on-Insulator Chips**, *Nawara Tanzee Minim, S M Enamul Hoque Yousuf, Yunong Wang, Philip Feng*, University of Florida

We present the integration and dynamic characterization of graphene membrane suspended over engineered dual-depth trench structures on a lithium niobate (LiNbO<sub>3</sub>) -on-insulator (LNOI) substrate for probing out-of-plane flexural resonances. The substrate comprises a 600 nm LiNbO<sub>3</sub> film atop 4.7  $\mu\text{m}$  thermally grown SiO<sub>2</sub> and a bulk silicon handle wafer, enabling piezoelectric compatibility and optical transparency. The device features rectangular trenches (12  $\mu\text{m}$  × 70  $\mu\text{m}$ , 300 nm deep) patterned via lithography and etching, with centrally embedded circular cavities (12  $\mu\text{m}$  diameter, 1.5  $\mu\text{m}$  deep) fabricates with focused ion beam (FIB) milling after carbon coating to introduce localized geometric perturbation. The structure is actuated using a broadband piezoelectric shaker coupled to the chip, inducing flexural motion across the suspended regions, and resonance modes are detected using laser interferometry. This architecture enables the comparative analysis of flexural eigenmodes in shallow vs. deep trench regions, highlighting the effect of local stiffness gradients, boundary conditions, and air damping. The use of LiNbO<sub>3</sub> as the underlying substrate introduces unique opportunities for acousto-optic and electro-mechanical coupling due to its strong piezoelectric and nonlinear optical properties. By leveraging the anisotropic elastic constants of LiNbO<sub>3</sub> and the high mechanical compliance of graphene, this platform facilitates the study of mode hybridization (coupling between localized modes of the deep circular trench and delocalized modes of the surrounding shallow trench, mediated by the continuous graphene membrane) and strain-tunable resonances through in-plan actuation of piezoelectric response in nanoscale membranes. Furthermore, the dual-depth trench geometry introduces spatially varying boundary stiffness, enabling mode localization and geometric control over frequency splitting. These architectures are compatible with SAW devices and LiNbO<sub>3</sub> photonic circuits, offering a pathway to integrated NEMS-photonic systems for sensing, transduction, and filtering applications.

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